

# Axiom Electronics PCBA Design for Manufacturability Guidelines

Section: 10.16

Revision: A

Revision Date: 2/14/13

DFM Subject: Via Placement and Spacing

DFM Requirement:

- Vias shall not be placed under leadless components (i.e. resistors, capacitors, etc.)
- Minimum via to via and via to land spacing shall be 0.25mm (0.010").

DFM Impact:

Placing vias under leadless components increases the risk of solder bridges and flux entrapment. Spacing vias too close together increases the risk of solder bridges.

DFM Details: Via Placement and Spacing

